

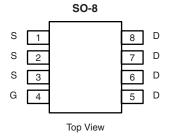
RoHS

COMPLIANT

Vishay Siliconix

N-Channel 30-V (D-S) MOSFET

PRODUCT SUMMARY						
V _{DS} (V)	R _{DS(on)} (Ω)	I _D (A)	Q _g (Typ.)			
30	0.0079 at V _{GS} = 10 V	19.3 ^a	8.8 nC			
30	0.010 at V _{GS} = 4.5 V	17.1 ^a	0.0 110			



FEATURES

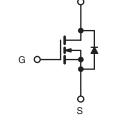
- Halogen-free
- TrenchFET[®] Power MOSFET
- 100 % R_g Tested
- 100 % UIS Tested

APPLICATIONS

- DC/DC
 - High Side
 - VRM



- Server



Ordering Information: Si4162DY-T1-GE3 (Lead (Pb)-free and Halogen-free)

N-Channel MOSFET

D

ABSOLUTE MAXIMUM RATINGS $T_A = 25 \degree C$, unless otherwise noted						
Parameter	Symbol	Limit	Unit			
Drain-Source Voltage	V _{DS}	30	V			
Gate-Source Voltage		V _{GS}			± 20	
	T _C = 25 °C		19.3 ^a			
Continuous Drain Current (T _{.1} = 150 °C)	T _C = 70 °C] , [15.4			
Continuous Drain Current $(T_J = 150 \text{ C})$	T _A = 25 °C	I _D	13.6 ^{b, c}	A		
	T _A = 70 °C	1	10.9 ^{b, c}	A		
Pulsed Drain Current		I _{DM}	70			
Avalanche Current	e Current L = 0.1 mH		31			
Avalanche Energy		E _{AS}	48	mJ		
Continuous Source-Drain Diode Current	T _C = 25 °C		4.2 ^a	Α		
Continuous Source-Drain Diode Current	T _A = 25 °C	I _S	2.1 ^{b, c}	A		
	T _C = 25 °C		5			
Maximum Power Dissinction	T _C = 70 °C		3.2	w		
Maximum Power Dissipation	T _A = 25 °C	P _D	2.5 ^{b, c}	VV		
	T _A = 70 °C		1.6 ^{b, c}			
Operating Junction and Storage Temperature	T _J , T _{stg}	- 55 to 150	°C			
Soldering Recommendations (Peak Tempera	Ŭ	260				

THERMAL RESISTANCE RATINGS

Parameter		Symbol	Typical	Maximum	Unit		
Maximum Junction-to-Ambient ^{b, d}	t ≤ 10 s	R _{thJA}	38	50 °C/			
Maximum Junction-to-Case (Drain)	Steady State	R _{thJC}	20	25			

Notes:

a. Based on T_C = 25 °C.

b. Surface Mounted on 1" x 1" FR4 board.

c. t = 10 s.

d. Maximum under Steady State conditions is 85 °C/W.

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Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_{D} = 250 \mu\text{A}$	30			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I _D = 250 μA		32		mV/°C	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I _D = 250 μA		- 5.5			
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_D = 250 \ \mu A$	1		3	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA	
	I _{DSS}	$V_{DS} = 30 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$			1	μA	
Zero Gate Voltage Drain Current		V_{DS} = 30 V, V_{GS} = 0 V, T_{J} = 55 °C			5		
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5$ V, V_{GS} = 10 V	50			А	
		V _{GS} = 10 V, I _D = 20 A			0.0079		
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = 4.5 V, I _D = 14 A		0.0082	0.010	Ω	
Forward Transconductance ^a	9 _{fs}	V _{DS} = 15 V, I _D = 20 A		70		S	
Dynamic ^b							
Input Capacitance	C _{iss}			1155			
Output Capacitance	C _{oss}	V _{DS} = 15 V, V _{GS} = 0 V, f = 1 MHz		260		pF	
Reverse Transfer Capacitance	C _{rss}			95			
Total Gate Charge		V _{DS} = 15 V, V _{GS} = 10 V, I _D = 20 A		20	20 30	nC	
	Qg			8.8	14		
Gate-Source Charge	Q _{gs}	V _{DS} = 15 V, V _{GS} = 4.5 V, I _D = 20 A		3.5			
Gate-Drain Charge	Q _{gd}			2.2			
Gate Resistance	R _g	f = 1 MHz		1.0	2.0	Ω	
Turn-On Delay Time	t _{d(on)}			20	30		
Rise Time	t _r	V_{DD} = 15 V, R_L = 15 Ω		15	25	-	
Turn-Off Delay Time	t _{d(off)}	$\text{I}_\text{D}\cong$ 1.0 A, V_GEN = 4.5 V, R_g = 17 Ω		25	40		
Fall Time	t _f			10	15		
Turn-On Delay Time	t _{d(on)}			14	20	ns	
Rise Time	t _r	$V_{DD} = 15 \text{ V}, \text{ R}_{\text{I}} = 15 \Omega$		9	15		
Turn-Off Delay Time	t _{d(off)}	$I_D \cong 1.0 \text{ A}, V_{GEN} = 10 \text{ V}, \text{ R}_g = 1 \Omega$		25	40		
Fall Time	t _f			9	15		
Drain-Source Body Diode Characteristi	cs						
Continuous Source-Drain Diode Current	۱ _S	T _C = 25 °C			30	•	
Pulse Diode Forward Current	I _{SM}				70	A	
Body Diode Voltage	V _{SD}	$I_{S} = 4.0 \text{ A}, V_{GS} = 0 \text{ V}$		0.8	1.2	V	
Body Diode Reverse Recovery Time	t _{rr}			21	42	ns	
Body Diode Reverse Recovery Charge	Q _{rr}	L = 4.0.4 dl/dt = 100.4/v; T = 05.00		15	30	nC	
Reverse Recovery Fall Time	ta	$I_F = 4.0 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 ^\circ\text{C}$		12.6		ns	
Reverse Recovery Rise Time	t _b			8.4			

Notes:

a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %.

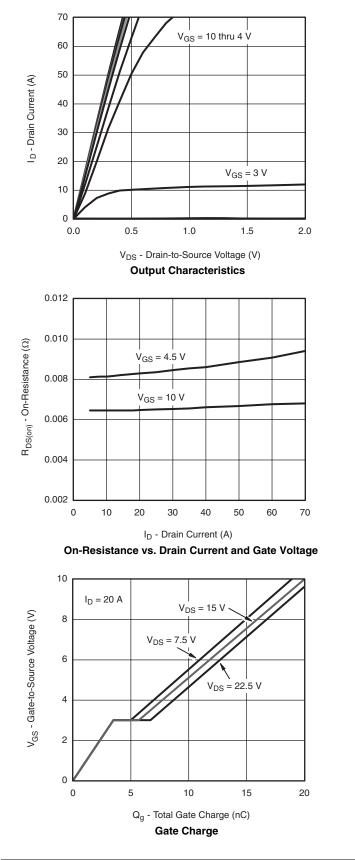
b. Guaranteed by design, not subject to production testing.

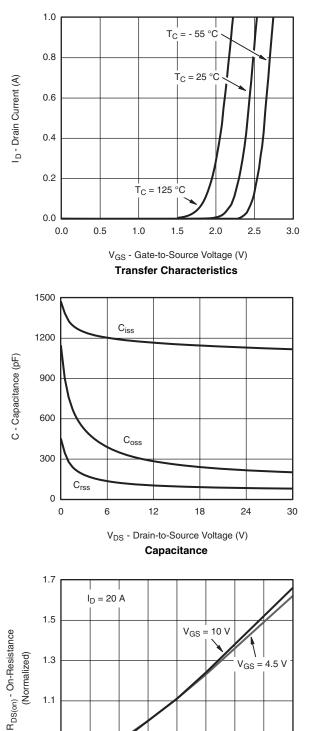
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted





0.9

0.7

- 50

- 25

0

25

50

T_J - Junction Temperature (°C)

On-Resistance vs. Junction Temperature

75

100

Document Number: 68967 S-82621-Rev. A, 03-Nov-08 125

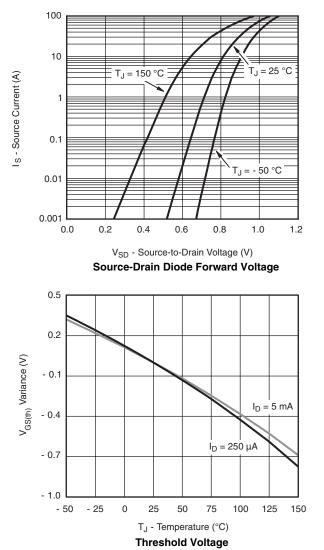
150

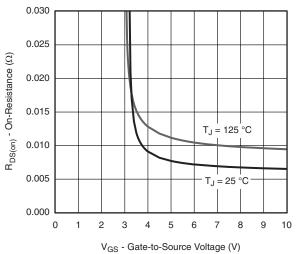
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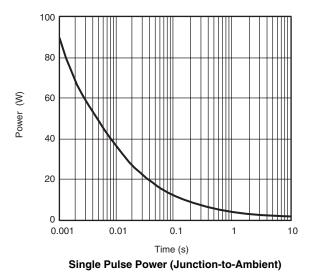


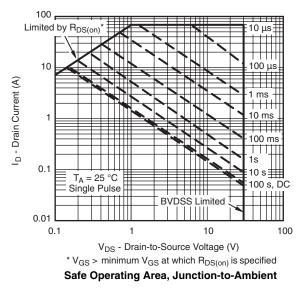
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted





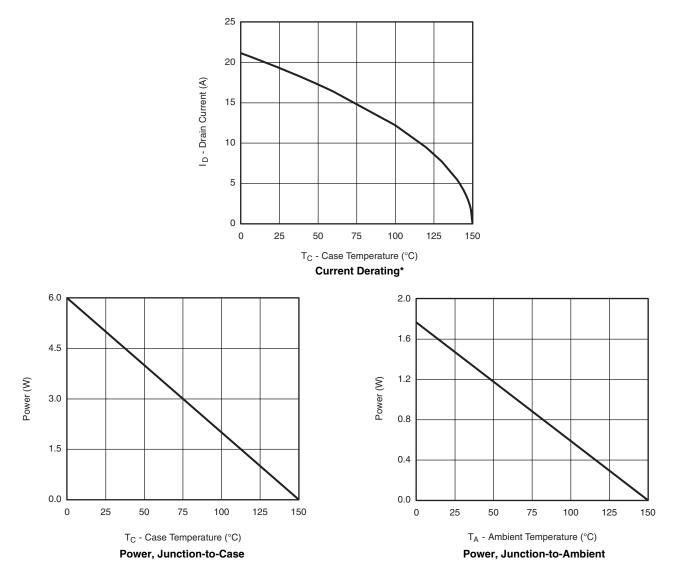
On-Resistance vs. Gate-to-Source Voltage







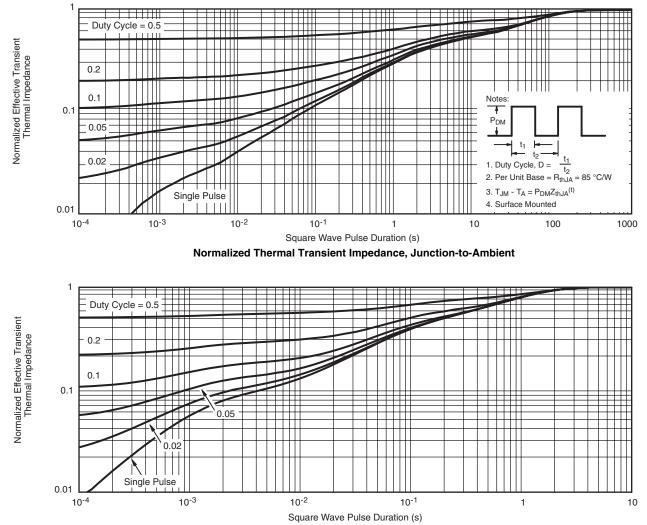
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



* The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

Vishay Siliconix





Normalized Thermal Transient Impedance, Junction-to-Foot

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see http://www.vishay.com/ppg?68967.



Package Information

Vishay Siliconix

SOIC (NARROW): 8-LEAD JEDEC Part Number: MS-012





	MILLIM	IETERS	INCHES		
DIM	Min	Мах	Min	Max	
A	1.35	1.75	0.053	0.069	
A ₁	0.10	0.20	0.004	0.008	
В	0.35	0.51	0.014	0.020	
С	0.19	0.25	0.0075	0.010	
D	4.80	5.00	0.189	0.196	
E	3.80	4.00	0.150	0.157	
е	1.27	BSC	0.050 BSC		
н	5.80	6.20	0.228	0.244	
h	0.25	0.50	0.010	0.020	
L	0.50	0.93	0.020	0.037	
q	0°	8°	0°	8°	
S	0.44	0.64	0.018	0.026	
ECN: C-06527-Rev. I, 11-Sep-06 DWG: 5498					

Application Note 826

Vishay Siliconix



RECOMMENDED MINIMUM PADS FOR SO-8



Recommended Minimum Pads Dimensions in Inches/(mm)

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